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August 2014

# FCA20N60 N-Channel SuperFET® MOSFET

**600 V, 20 A, 190 m**Ω

### **Features**

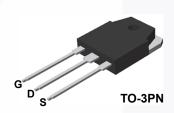
- 650V @ T<sub>J</sub> = 150°C
- Typ.  $R_{DS(on)}$  = 150 m $\Omega$
- Ultra Low Gate Charge (Typ.  $Q_g$  = 75 nC )
- Low Effective Output Capacitance (Typ. C<sub>oss(eff.)</sub> = 165 pF)
- · 100% Avalanche Tested

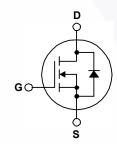
### **Applications**

- · Solar Inverter
- AC-DC Power Supply

# **Description**

SuperFET® MOSFET is Fairchild Semiconductor's first generation of high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low onresistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. Consequently, SuperFET MOSFET is very suitable for the switching power applications such as PFC, server/telecom power, FPD TV power, ATX power and industrial power applications.





### MOSFET Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted.

Symbol			FCA20N60 / FCA20N60_F109	Unit		
$V_{DSS}$	Drain to Source Voltage			600	V	
$V_{GSS}$	Gate-Soure voltage			±30	V	
	Drain Current	- Continuous (T <sub>C</sub> = 25°C)		20	_	
I <sub>D</sub>	DrainCurrent	- Continuous (T <sub>C</sub> = 100°C)	- Continuous (T <sub>C</sub> = 100°C)		A	
I <sub>DM</sub>	Drain Current	- Pulsed	(Note 1)	60	Α	
E <sub>AS</sub>	Single Pulsed Avalanche E	nergy	(Note 2)	690	mJ	
I <sub>AR</sub>	Avalanche Current		(Note 1)	20	Α	
E <sub>AR</sub>	Repetitive Avalanche Ener	gy	(Note 1)	20.8	mJ	
dv/dt	Peak Diode Recovery dv/d	t	(Note 3)	4.5	V/ns	
Б	Dawer Dissipation	(T <sub>C</sub> = 25°C)		208	W	
$P_{D}$	Power Dissipation  - Derate Above 25°C			1.67	W/°C	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Ter	nperature Range		-55 to +150	°C	
T <sub>L</sub>	Maximum Lead Temperatu	re for Soldering, 1/8" from Case for 5 \$	Seconds	300	°C	

### **Thermal Characteristics**

Symbol	Parameter	FCA20N60 / FCA20N60_F109	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.6	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	41.7	*C/VV

# **Package Marking and Ordering Information**

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FCA20N60	FCA20N60	TO-3PN	Tube	N/A	N/A	30 units
FCA20N60_F109	FCA20N60	TO-3PN	Tube	N/A	N/A	30 units

# **Electrical Characteristics** $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	cteristics					
D\/	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V, T_J = 25^{\circ} C$	600	-	-	V
$BV_{DSS}$	Dialii to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V, T_J = 150^{\circ} C$	-	650	-	V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, Referenced to 25°C	-	0.6	-	V/°C
BV <sub>DS</sub>	Drain-Source Avalanche Breakdown Voltage	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 20 A	_	700	-	V
	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V	-	-	1	^
IDSS	Zero Gate voltage Drain Current	$V_{DS} = 480 \text{ V}, T_{C} = 125^{\circ}\text{C}$	-	-	10	μА
I <sub>GSS</sub>	Gate to Body Leakage Current	V <sub>GS</sub> = ±30 V, V <sub>DS</sub> = 0 V	-	-	±100	nA

### **On Characteristics**

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu\text{A}$	3.0	-	5.0	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$	-	0.15	0.19	Ω
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 40 V, I <sub>D</sub> = 10 A	-	17	-	S

### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	05.777	- \	2370	3080	pF
C <sub>oss</sub>		V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1 MHz	-	1280	1665	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 1 1011 12	-	95	-	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = 480 V, V <sub>GS</sub> = 0 V, f = 1 MHz	-	65	85	pF
C <sub>oss(eff.)</sub>	Effective Output Capacitance	V <sub>DS</sub> = 0 V to 400 V, V <sub>GS</sub> = 0 V	-	165	-	pF
$Q_g$	Total Gate Charge at 10V	V <sub>DS</sub> = 480 V, I <sub>D</sub> = 20 A,	-	75	98	nC
$Q_{gs}$		V <sub>GS</sub> = 10 V	- /	13.5	18	nC
$Q_{gd}$	Gate to Drain "Miller" Charge	(Note 4)	- /	36	ı	nC

### **Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time		/-	62	135	ns
t <sub>r</sub>	Turn-On Rise Time	V <sub>DD</sub> = 300 V, I <sub>D</sub> = 20 A,	-	140	290	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS}$ = 10 V, $R_G$ = 25 $\Omega$	-	230	470	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4)	-	65	140	ns

#### **Drain-Source Diode Characteristics**

I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	20	Α
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	60	Α
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{SD} = 20 \text{ A}$	-	-	1.4	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 20 A,	-	530	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	$dI_F/dt = 100 A/\mu s$	-	10.5	_	μC

#### Notes:

- 1: Repetitive rating: pulse-width limited by maximum junction temperature.
- 2:  $I_{AS}$  = 10 A,  $V_{DD}$  = 50 V,  $R_G$  = 25  $\Omega$ , starting  $T_J$  = 25°C.
- 3: I  $_{SD}~\leq 20$  A, di/dt  $\leq 200$  A/µs, V  $_{DD} \leq BV _{DSS},$  starting T  $_{J}$  = 25°C.
- 4: Essentially independent of operating temperature typical characteristics.

# **Typical Performance Characteristics**

Figure 1. On-Region Characteristics

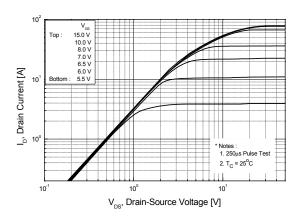


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

10<sup>2</sup>

10<sup>1</sup>

150°C

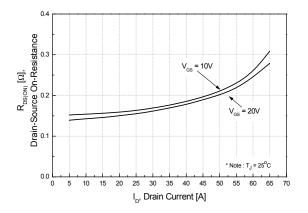
25°C

Note
1. V<sub>os</sub> + 40V
2. 250µs Pulse Test

V<sub>os</sub> , Gate-Source Voltage [V]

Figure 2. Transfer Characteristics

Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperatue



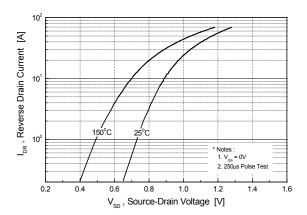


Figure 5. Capacitance Characteristics

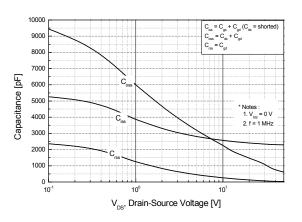
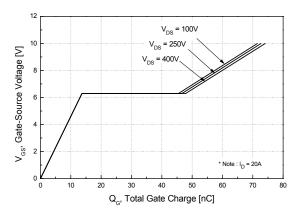


Figure 6. Gate Charge Characteristics



# **Typical Performance Characteristics** (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

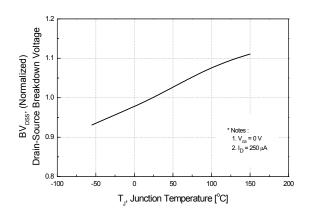


Figure 8. On-Resistance Variation vs. Temperature

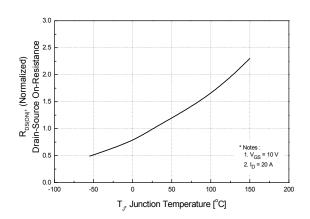


Figure 9. Maximum Safe Operating Area

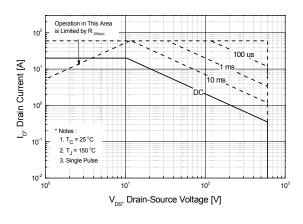


Figure 10. Maximum Drain Current vs. Case Temperature

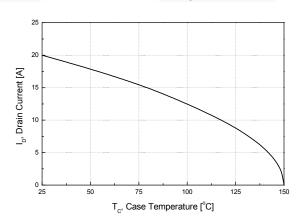
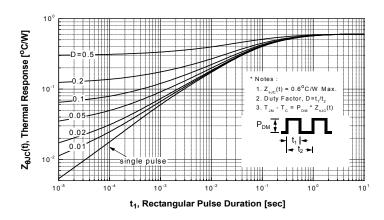


Figure 11. Transient Thermal Response Curve



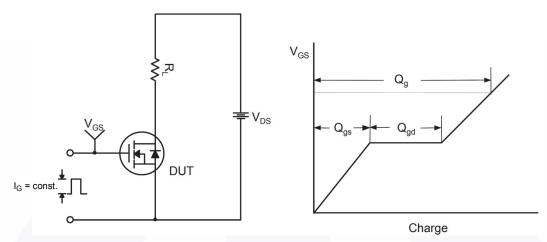


Figure 12. Gate Charge Test Circuit & Waveform

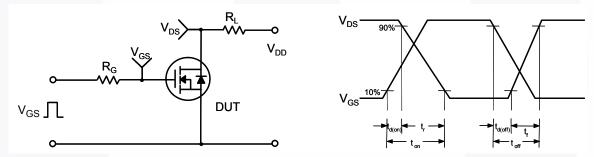


Figure 13. Resistive Switching Test Circuit & Waveforms

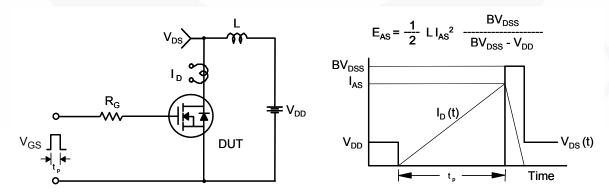


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

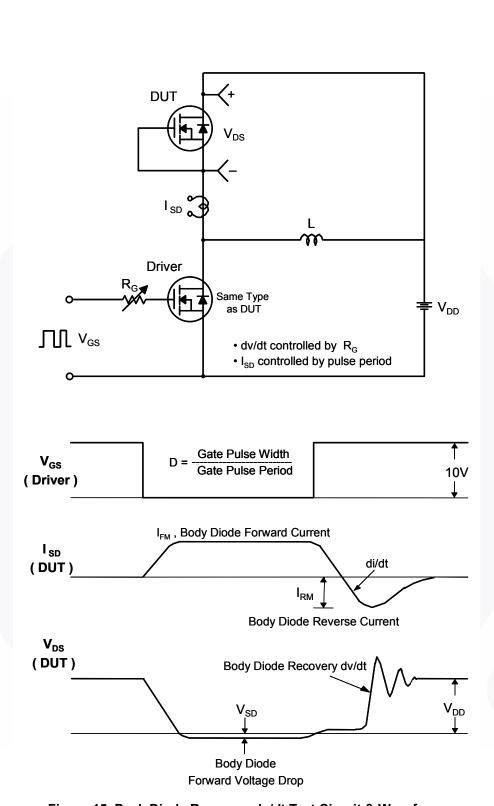
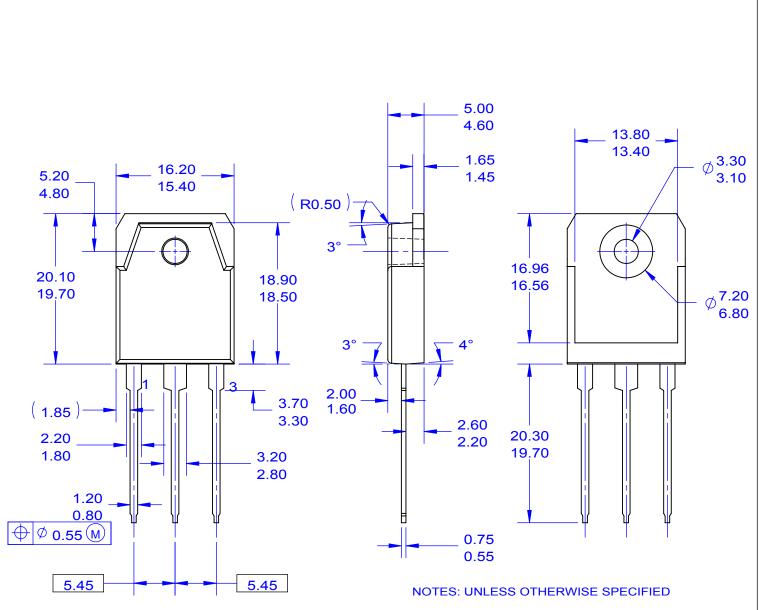
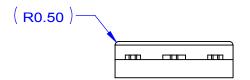


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms





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